

/ Descriptions

PDFN5×6 N

N-Channel MOSFET in a PDFN5×6 Plastic Package.

/ Features

$V_{DS}(V)=500V$ $I_D=1.7A$

$R_{DS(ON)}@10V \leq 3.5\Omega$ (Typ. 2.8Ω)

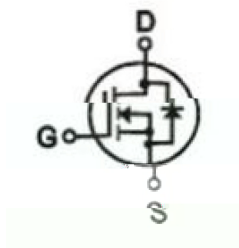
Fast Switching.

HF Product.

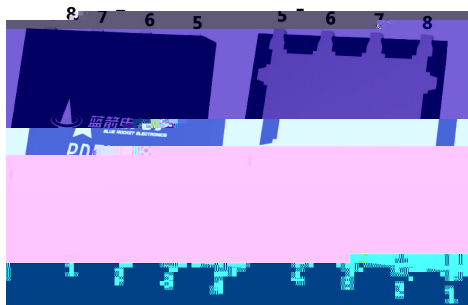
/ Applications

These devices are well suited for power switch circuit of adaptor and charger, intergrate fast recovery diode.

/ Equivalent Circuit



/ Pinning



PIN1 2 3 S PIN4 G PIN5 6 7 8 D

/ Marking

See Marking Instructions.

Parameter	Symbol	Rating	Unit
Drain-Source Voltage	V_{DS}	500	V
Drain Current	$I_D(T_c=25\text{ }^{\circ}\text{C})$	1.7	A
Drain Current - Pulsed	I_{DM}	5.5	A
Gate-Source Voltage	V_{GS}	± 30	V
Single Pulsed Avalanche Energy	E_{AS}	112.5	mJ
Avalanche Current	I_{AS}		

/ Electrical Characteristic Curve

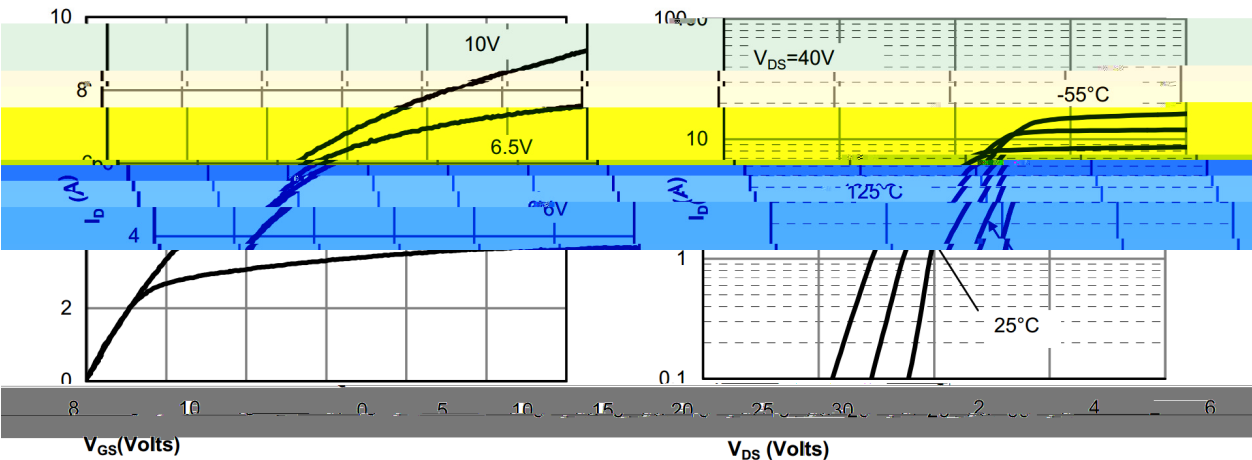


Figure 2: Transfer Characteristics

Figure 1: On-Region Characteristics

Figure 1

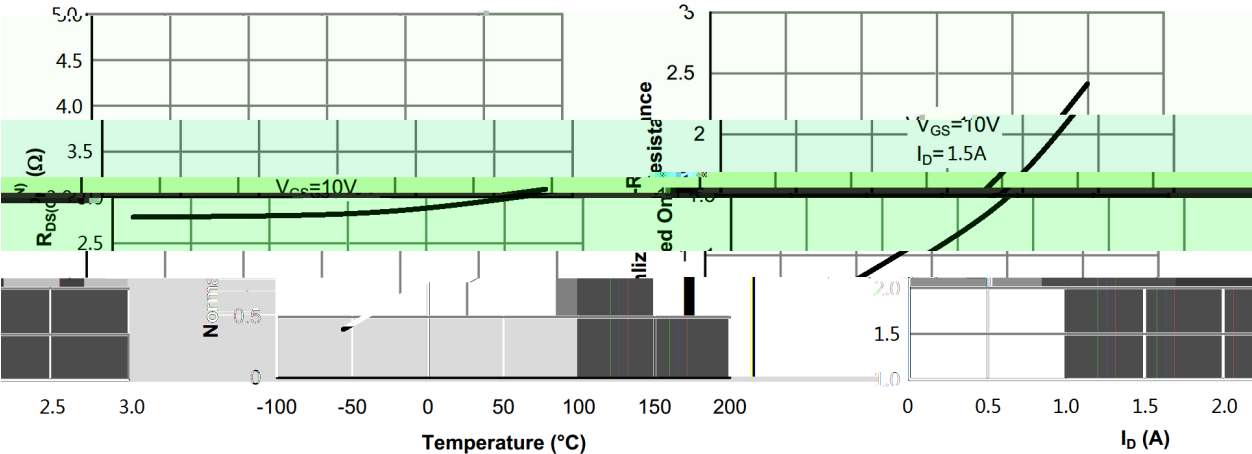
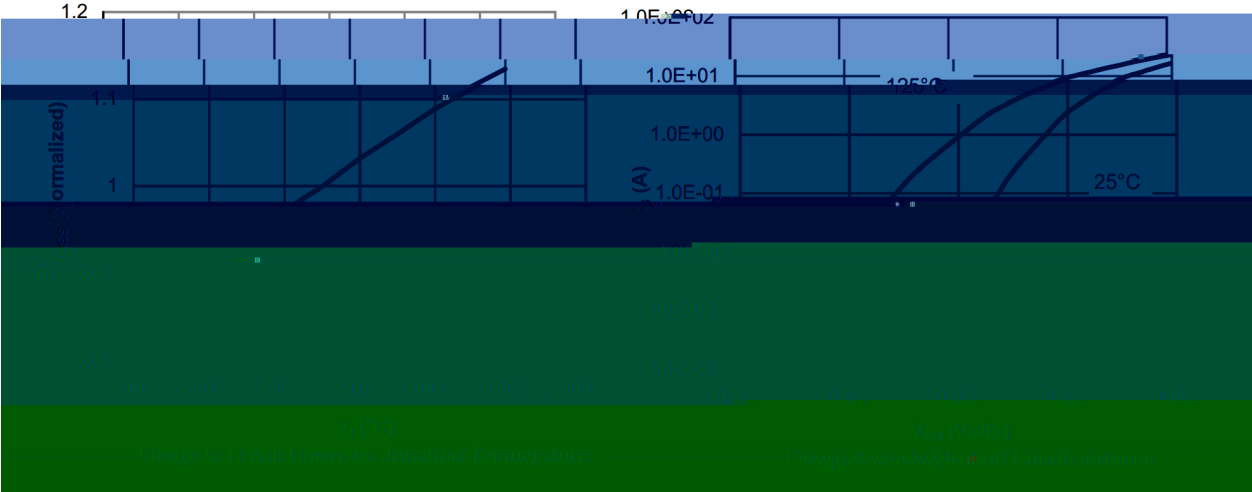


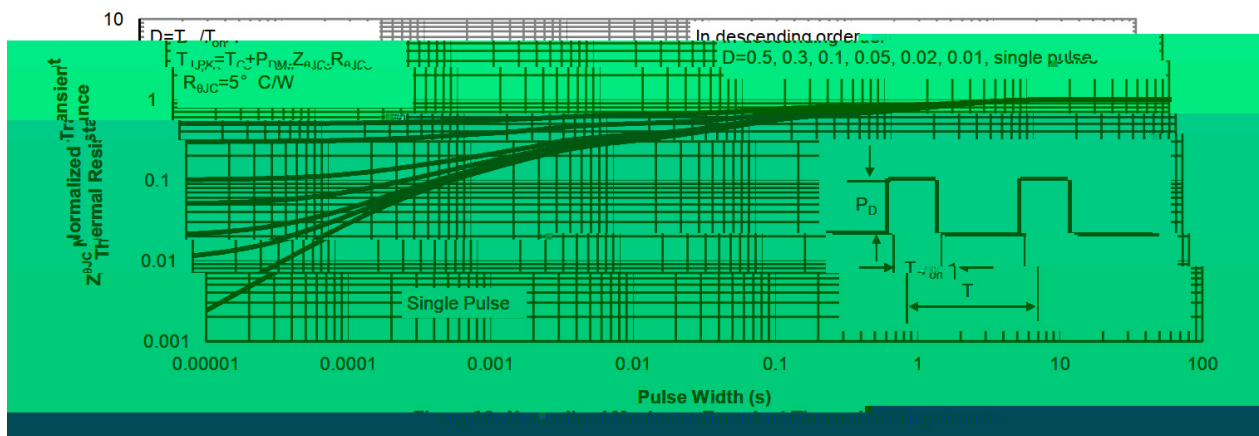
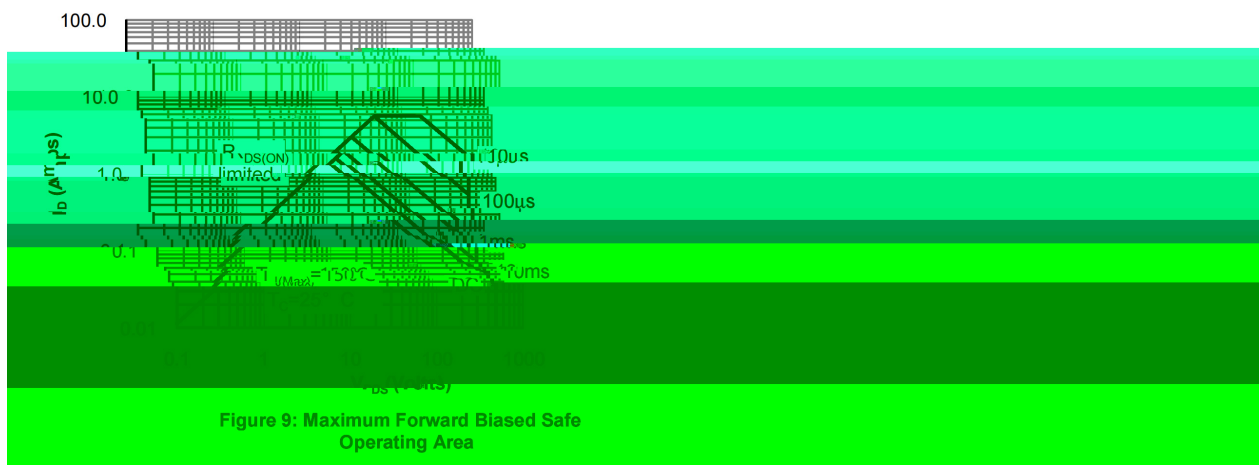
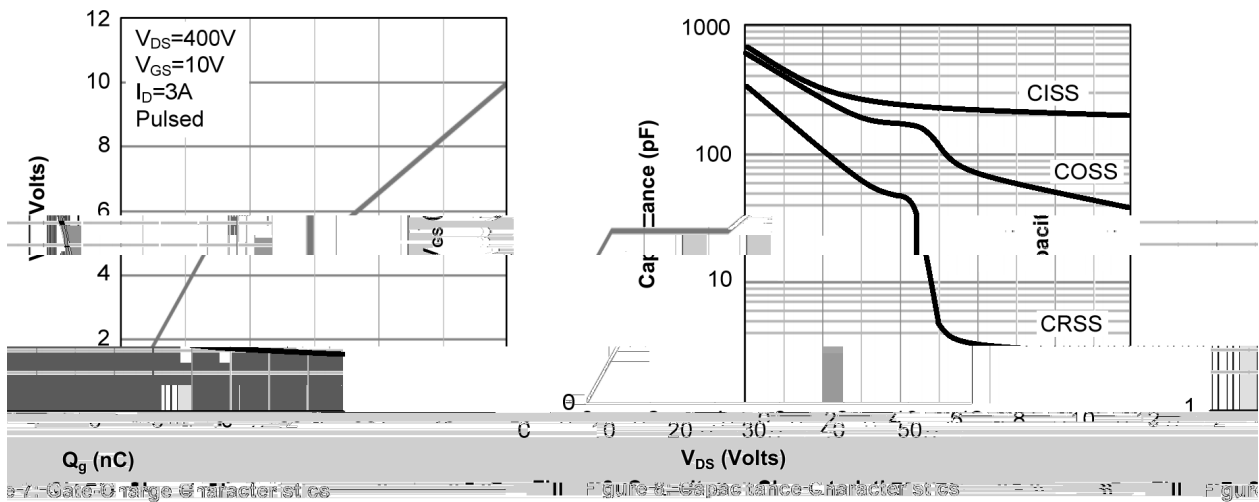
Figure 3: On-Resistance vs. Drain Current

Figure 4: On-Resistance vs. Temperature

Figure 2: On-Resistance vs. Drain Current

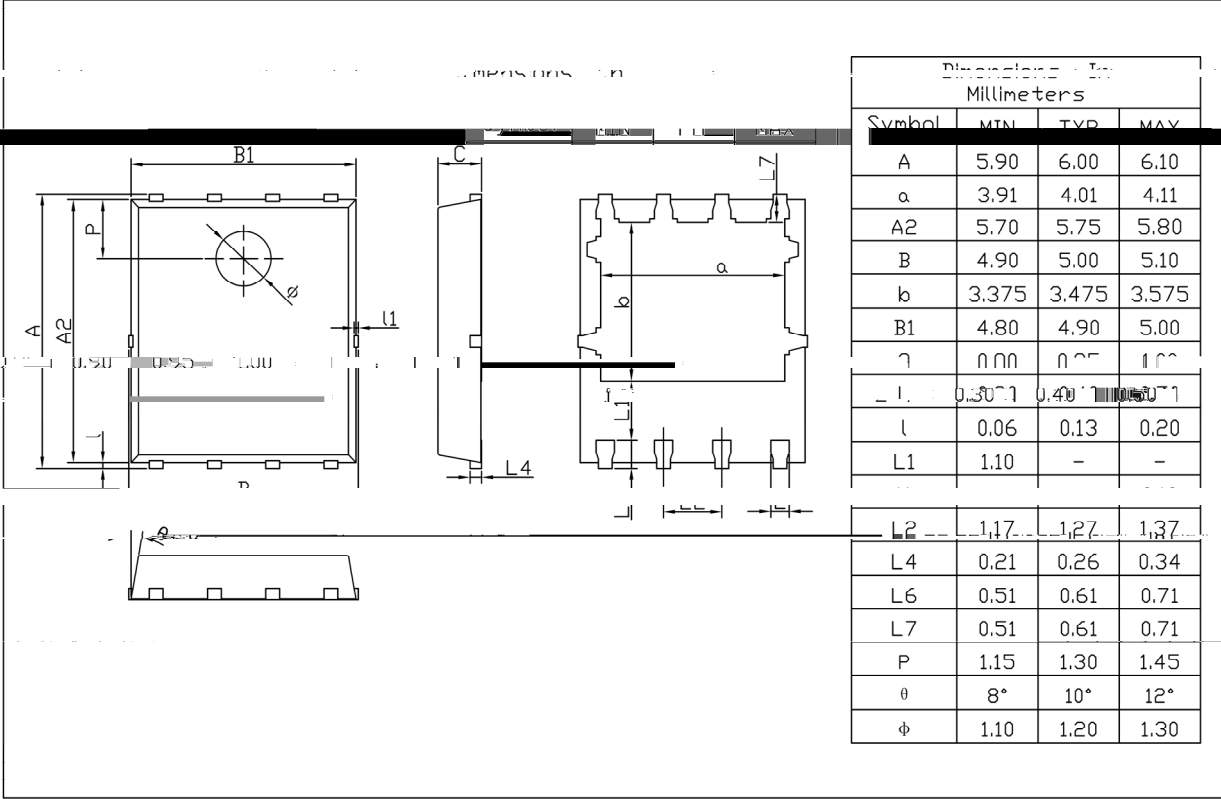


/ Electrical Characteristic Curve



I Package Dimensions

PDFN5 X6Unit:mm



Rev.01 202209

/ Marking Instructions



BR

3N50AF

Note

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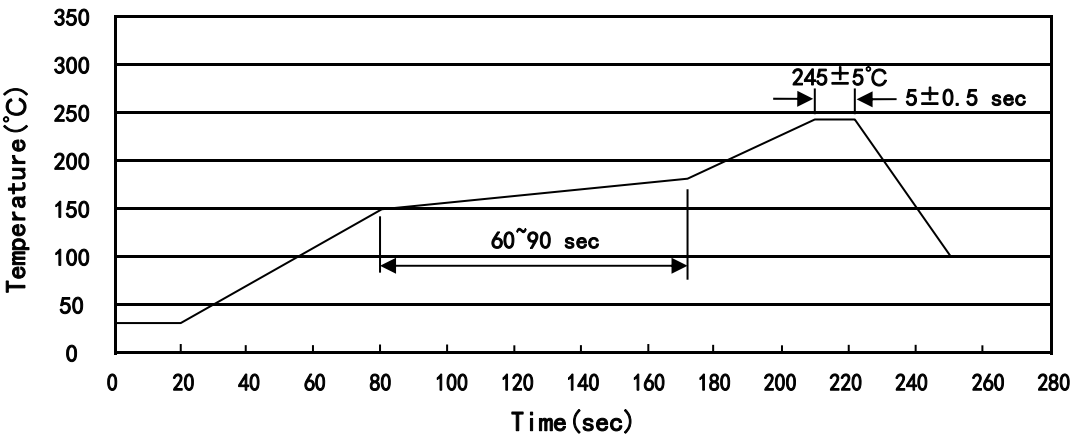
Company Code

3N50AF

Product Type Code

Lot No. Code, code change with Lot No

() / Temperature Profile for IR Reflow Soldering(Pb-Free)



Note:

- 1

150 180

60 90sec;

1.Preheating:150~180 , Time:60~90sec.
- 2

245±5

5±0.5sec;

2.Peak Temp.:245±5 , Duration:5±0.5sec.
- 3

2 10

/sec.

3. Cooling Speed: 2~10 /sec.

/ Resistance to Soldering Heat Test Conditions

260±5 10±1 sec. Temp.:260±5 Time:10±1 sec

/ Packaging SPEC.

/ REEL

Package Type	Units					Dimension (unit mm ³)		
	Units/Reel /	Reels/Inner Box /	Units/Inner Box /	Inner Boxes/Outer Box /	Units/Outer Box /	Reel	Inner Box	Outer Box
PDFN5×6	5,000	2	10,000	6	60,000	13"×12	360×360×50	380×335×366

/ Notices